

WHAT IS CLAIMED IS:

1           1. A chip device comprising:  
2           a. a die; and  
3           b. a leadframe including a die attach cavity, the die attach cavity  
4           having substantially the same thickness as the die;  
5           c. wherein the die is positioned within the die attach cavity and is  
6           attached therein.

1           2. The chip device of claim 1 further comprising a plurality of  
2           dimples defined around the periphery of the leadframe that receive solder balls.

1           3. The chip device of claim 1 wherein the leadframe consists of a  
2           copper based alloy.

1           4. The chip device of claim 3 wherein the leadframe includes a  
2           solderable coating.

1           5. The chip device of claim 1 wherein the die is a bumped die.

1           6. A chip device comprising:  
2           a. a bumped die;  
3           b. a leadframe including a die attach cavity and a plurality of dimples  
4           defined around a periphery of the leadframe, the die attach cavity having substantially the  
5           same thickness as the die; and  
6           c. a plurality of solder balls placed within the dimples;  
7           wherein the die is positioned within the cavity and is attached  
8           therein.

1           7. The chip device of claim 6 wherein the leadframe consists of a  
2           copper based alloy.

1               8.     The chip device of claim 7 wherein the leadframe includes a  
2 solderable coating.

1               9.     A method of making a chip device, the method comprising:  
2               providing a die;  
3               providing a leadframe including a die attach cavity and a plurality of  
4               dimples defined around a periphery of the leadframe, the die attach cavity having  
5               substantially the same thickness as the die;  
6               placing solder balls into the dimples; and  
7               flipping the die into the die attach cavity and attaching it therein.

1               10.    The method of claim 9 wherein the die provided is a bumped die.